

FLOPACK Version 6.2 released

Flomerics is pleased to announce the release of FLOPACK Version 6.2, with enhanced performance, support for even more package families, and other exciting new features.

HEADLINE ITEMS

- **New package families** : FLOPACK continues to support new package families with every release. This release further enhances our offering of discrete/power package portfolio.
 - ◆ SOT-23
 - ◆ SOT-223
 - ◆ BOC and Powerquad smartparts now support Delphi
 - ◆ Compact models
- **Sanity checks on package design sheets** : The last release featured sanity checks for the package smartpart wizards. In this release, a much more extensive set of sanity checks has been implemented directly at the design sheet level. Minimize your data entry errors with this new feature!
- **Underfill option for two-resistor model calculation** : Two-resistor model submissions now come with an option for adding underfill to the Theta-JB (Ring Cold Plate) test.

MORE NEW FEATURES

- **Other new features** :
 - User-to-user send feature now includes compact models
 - Stiffener option provided for lid in all Flip-Chip packages
 - Depopulation utility for vias in Flip-Chip PBGA is available
 - Bond-wire model has been enhanced for all packages
 - Multiple die sources can now each be given a name in the CSV file
 - "Add test" PDML file name has been customized
 - Junction temperature monitor point in a die is now positioned on the die surface, rather than the die center. This is a more accurate representation.

- **Bug-fixes** : Several outstanding bugs have now been fixed
 - Two Resistor Model (Vendor Provided) now works as designed
 - Localized grid constraints attached to the model option deactivation now works as designed
 - PDIP bond-wire construction is corrected when die plane is above the Leadframe plane
 - Coarse grid density option in localized grid constraints attached to the model now works
 - JEDEC test board sizes corrected
 - Depopulate via array for JEDEC test environment now works as designed
 - New BC file uploading for customized Delphi setup parameters option now works
 - The "Attach" button in material dialogue window now attaches the material and also closes the dialogue window
 - The Approximate option in modeling the leadframe in TSOP/SOP smartpart can give large errors, and has been removed